OL-PN550

wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included)

8 February 2016 | Package information

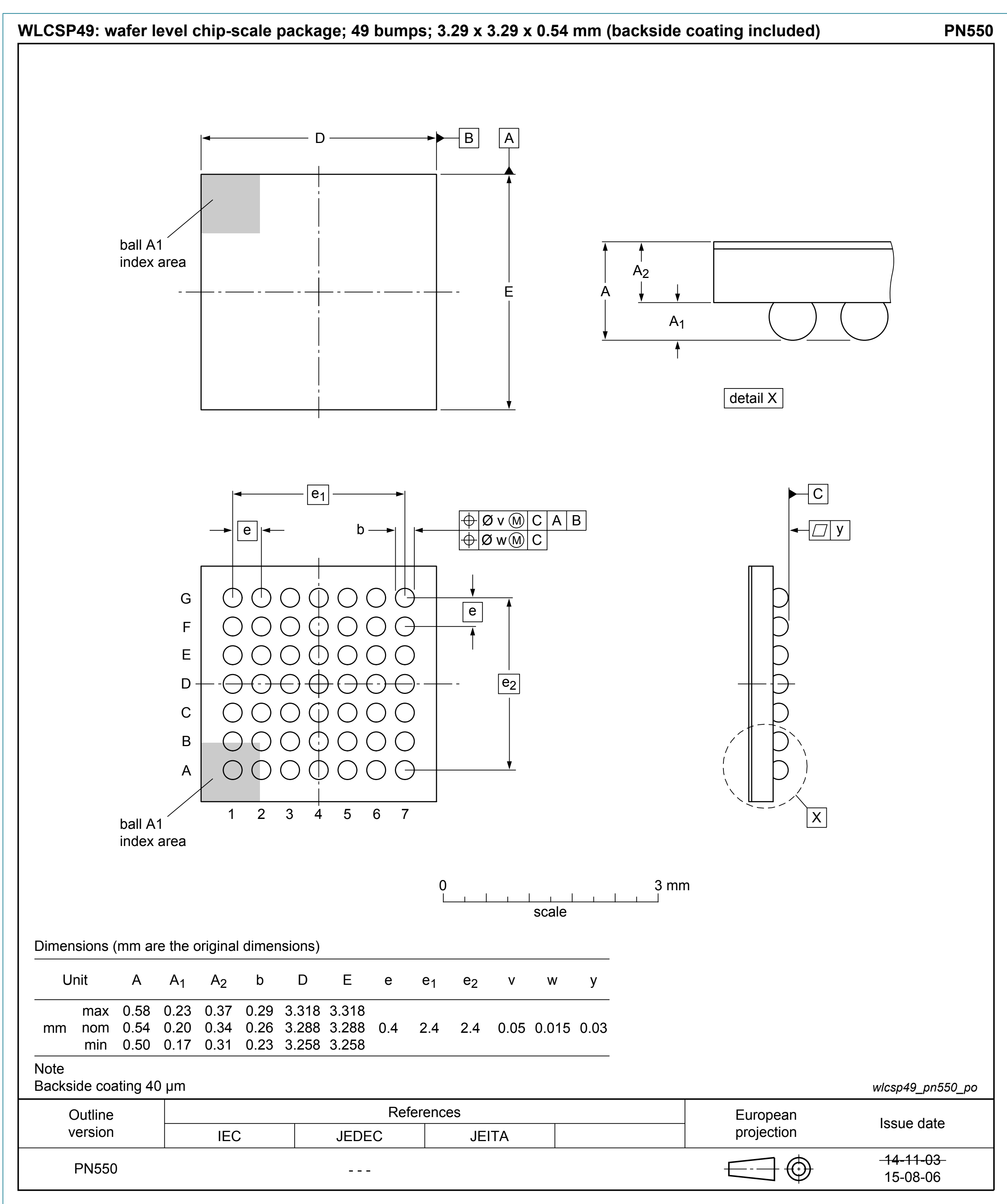
1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP49
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-8-2015

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.258	-	3.288	3.318	mm
E	package width		3.258	-	3.288	3.318	mm
A	seated height		0.5	-	0.54	0.58	mm
A_2	package height		0.31	-	0.34	0.37	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	49	-	

2. Package outline



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y
	max	0.58	0.23	0.37	0.29	3.318	3.318						
mm	nom	0.54	0.20	0.34	0.26	3.288	3.288	0.4	2.4	2.4	0.05	0.015	0.03
	min	0.50	0.17	0.31	0.23	3.258	3.258						

Note
Backside coating 40 µm

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
PN550		- - -				~~14-11-03~~ 15-08-06

Fig. 1. Package outline WLCSP49 (OL-PN550)

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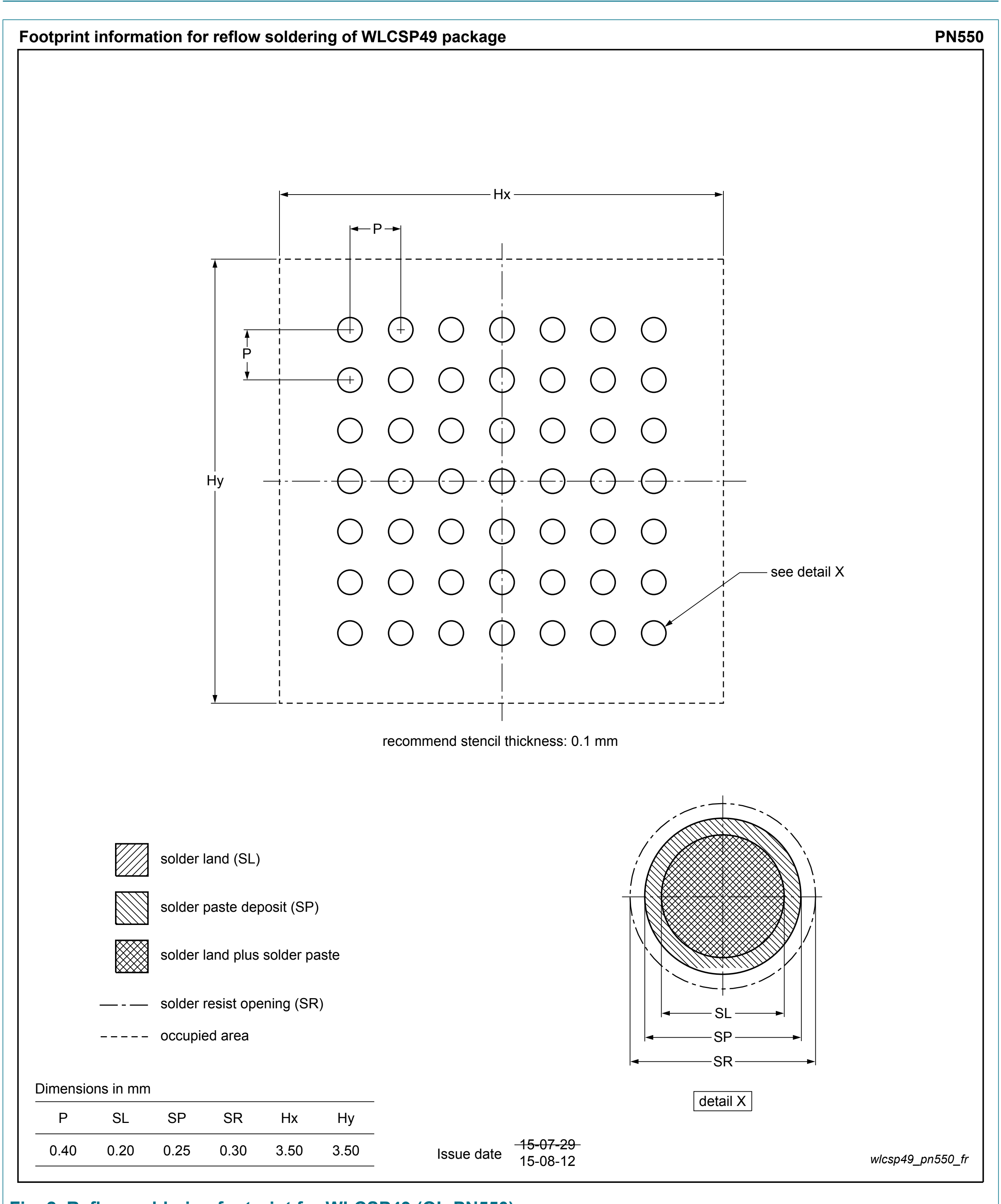
3. Soldering



P	SL	SP	SR	Hx	Hy
0.40	0.20	0.25	0.30	3.50	3.50

Fig. 2. Reflow soldering footprint for WLCSP49 (OL-PN550)

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5. Contents

1. Package summary... 1
2. Package outline.. 2
3. Soldering.. 3
4. Legal information.. 4

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